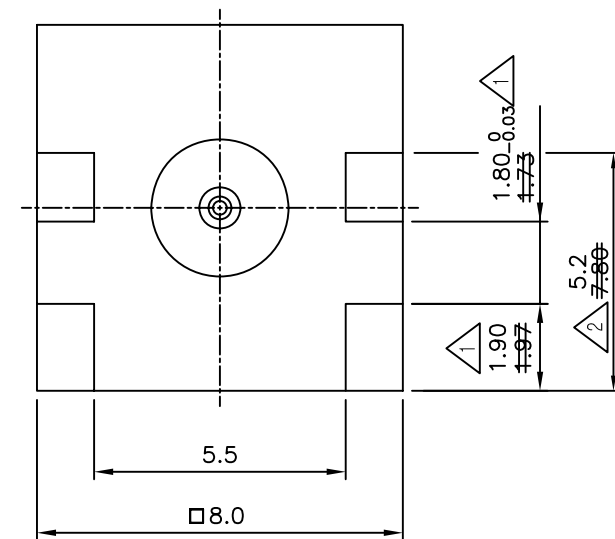
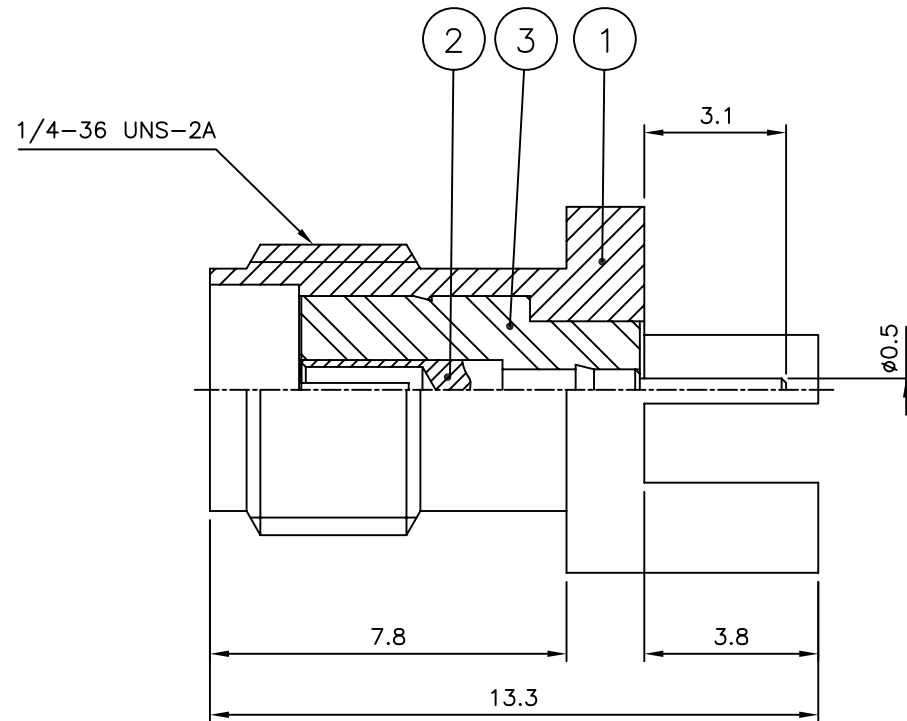


REVISION					
REV	DESCRIPTION	DRAWN	APPR	DATE	
IR	Initial Registration	E.H.KIM	I.C.KIM	2012.12.21.	
1	[설번처리No.201301-0008] 조립성 향상 (PCB 삽입부 치수 변경)	E.H.KIM	I.C.KIM	2013.01.14.	
2	[설번처리No.201605-0013] 도면상 치수 오기입으로 인한 치수 수정	C.K.KIM	I.C.KIM	2016.05.26.	



3	INSULATOR	1	TEFLON		DIN02022-N/1
2	CONTACT	1	BeCu	Gold Plate	DCT02615-5/1
1	BODY	1	MBsBD	Gold Plate	DBD03226-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 05. 26.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	H.J.LEE	KJ COMTECH CO.,LTD. TITLE SMA50 PCB JS-4R (edge) PCB
		DRAWN BY	C.K.KIM	
FINISH		SCALE	UNIT	A4 DWG NO. CN02911-7/1 REVISION 2 SHEET 1 of 1
		6/1	mm	